

REMARKS

Claims 1-18 are currently pending in the application, of which claims 1, and 7 and 14 are independent claims. By this amendment, the specification is amended to correct a minor oversight. No amendments have been made to the claims. In view of the above amendments and the following Remarks, Applicants respectfully request reconsideration and timely withdrawal of the pending objections and rejections for the reasons discussed below.

Drawing Objections

The drawings were objected to for not including a reference numeral in the description. Applicants have amended paragraph 22 to include reference character 34 of Fig. 8. Therefore, Applicants respectfully submit that the objection to the drawings is overcome and request that the objection be withdrawn.

Allowable Subject Matter

Applicants appreciate the indication that claims 7-13 contain allowable subject matter. Applicants also appreciate the indication that claims 14-18 are allowed.

Rejections Under 35 U.S.C. §102

Claims 1-6 stand rejected under 35 U.S.C. §102(b) as being anticipated by U. S. Patent No. 6,228,694 issued to Doyle, *et al.* ("Doyle"). Applicants respectfully traverse this rejection for at least the following reasons.

The Examiner is of the opinion that the Doyle reference includes the features of claims 1-6. Specifically, the Examiner is of the opinion that Doyle discloses, at least, "expanding a first region of a substrate to push up a first portion of the semiconductor layer," and "compressing a

second region of the substrate to pull down a second portion of the semiconductor layer,” as required by claim 1. Applicants do not agree with the Examiner.

By way of illustration, Doyle does not disclose “expanding a first region of a substrate to push up a first portion of the semiconductor layer,” and “compressing a second region of the substrate to pull down a second portion of the semiconductor layer.” Rather Doyle only describes:

“forming voids in a region of a substrate to modify the localized stresses of the region such that the carrier mobility of a device fabricated on the substrate is also modified.”

Doyle at col. 3, ll. 54-57.

Doyle contains no reference to expanding or compressing any regions in a substrate. Also, forming the voids is not the same as that of expanding and compressing as recited in the invention. The Office Action fails to identify any portion of Doyle that contains such a disclosure.

Therefore, for at least this reason, Doyle does not disclose every element of claim 1. Accordingly, Applicants respectfully request withdrawal of the 35 U.S.C. §102(b) rejection of claims 1-6. Since none of the other prior art of record discloses or suggests all the features of the claimed invention, Applicants respectfully submit that independent claim 1, and all the claims that depend therefrom are patentable over the prior art of record.

CONCLUSION

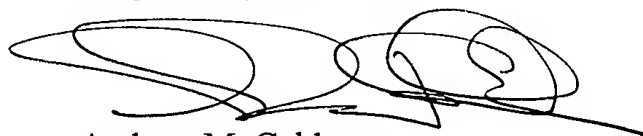
Applicants believe that a full and complete response has been made to the pending Office Action and respectfully submits that all of the stated objections and grounds for rejection have been overcome or rendered moot. Accordingly, Applicants respectfully submit that all pending claims are allowable and that the application is in condition for allowance, and request that the objections and rejections be reconsidered and withdrawn. Should the Examiner feel that there are any issues outstanding after consideration of this response, the Examiner is invited to contact the Applicants' undersigned representative at the number below to expedite prosecution.

Prompt and favorable consideration of this Reply is respectfully requested.

Please charge any deficiencies in fees and credit any overpayment of fees to **IBM**

Deposit Account No. 09-0458 (Fishkill).

Respectfully submitted,



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